10/076, 244

L Number	Hits	Search Text	DB	Time stamp
1	5	((polyacetylene (polyparaphenylene adj vinylene) ppv polyaniline) near4	USPAT;	2004/03/01 15:31
-		dope\$2) and @ad<20000707 and (polymer near3 (plug ball bump))	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT,	
			IBM_TDB	
2	2	("4692225").PN.	USPAT;	2004/03/01 15:32
			US-PGPUB;	•
			ЕРО; ЛРО;	
		·	DERWENT;	
			IBM_TDB	
3	1	(("4692225").PN.) and dope\$2	USPAT;	2004/03/01 15:32
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
	10	((#5000055#)	IBM_TDB	2004/02/01 12:24
-	12	(("5923955") or ("5891756") or ("5795818") or ("5904859") or	USPAT;	2004/03/01 12:34
	•	("5767009") or ("5804876")).PN.	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	0	((nickel adj carbonyl) nico4) and @ad<20020213 and ((polymer epoxy	USPAT;	2004/02/24 15:33
-	U	dielectric) adj plug) and (semiconductor chip die dice ic (integrated adj	US-PGPUB;	200-1102127 13.33
		circuit))	ЕРО; ЛРО;	
		onoun,)	DERWENT;	
			IBM_TDB	
_	1009	((nickel adj carbonyl) nico4) and @ad<20020213	USPAT;	2004/02/24 15:33
	1007	((inote) and carbonyly into 1) and again 20020210	US-PGPUB;	
			ЕРО; ЛРО;	
		·	DERWENT;	
1			IBM_TDB	
-	159	(((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor	USPAT;	2004/02/24 15:34
		chip die dice ic (integrated adj circuit))	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	2004/02/24
-	0	((((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor	USPAT;	2004/02/24 15:34
	4	chip die dice ic (integrated adj circuit))) and ((copper cu) near3 (bump	US-PGPUB;	
		ball))	ЕРО; ЛРО;	
			DERWENT; IBM_TDB	
	150	(((nickel adj carbonyl) nico4) and @ad<20020213) and (semiconductor	USPAT;	2004/02/24 17:07
•	159	chip die dice ic (integrated adj circuit))	US-PGPUB;	2007/02/27 17.07
		omp are aree to (magnated auj encure))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2560	((438/108) or (257/778)).CCLS.	USPAT;	2004/02/24 17:08
		(US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
-	165	(((438/108) or (257/778)).CCLS.) and @ad<20020213 and ((ball bump)	USPAT;	2004/02/25 12:01
		near3 (polymer epoxy)) and conductive	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
-	165	(((438/108) or (257/778)).CCLS.) and @ad<20020213 and ((ball bump)	USPAT;	2004/02/25 12:02
		near3 (polymer epoxy)) and conductive	US-PGPUB;	
			EPO; JPO;	
		,	DERWENT;	
			IBM_TDB	

-	17	(polyacetylene (polyparaphenylene adj vinylene) ppv polyaniline) and @ad<20000707 and (polymer near3 (plug ball bump))	USPAT; US-PGPUB;	2004/03/01 15:26
		(Wad-20000 70 7 and (porymer near) (plug ban bump))	ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	